

TENTATIVE

TOSHIBA GATE TURN-OFF THYRISTOR

SG4500GXH25

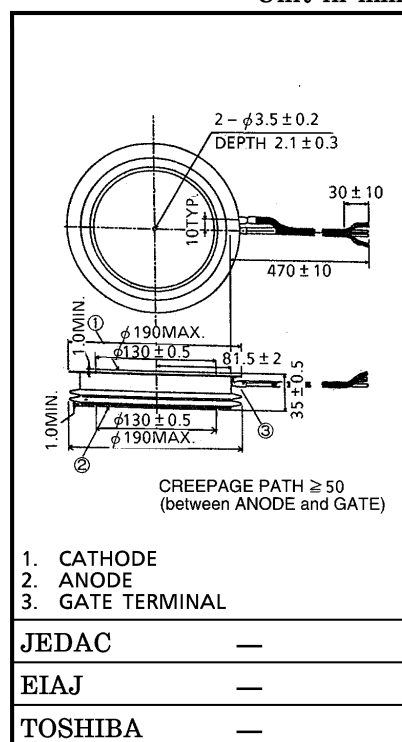
INVERTER APPLICATION

Unit in mm

- Repetitive Peak Off-State Voltage : $V_{DRM}=4500V$
(Note 1)
- Repetitive Peak Reverse Voltage : $V_{RRM}=4000V$
- R.M.S On-State Current : $I_T(RMS)=3000A$
- Peak Turn-Off Current : $I_{TGQM}=4500A$
- Critical Rate of Rise of On-State Current : $di/dt=300A/\mu s$
- Critical Rate of Rise of Off-State Voltage : $dv/dt=1000V/\mu s$

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Off-State Voltage (Note 1)	V_{DRM}	4500	V
Repetitive Peak Reverse Voltage	V_{RRM}	4000	V
Peak Turn-Off Current (Note 2)	I_{TGQM}	4500	A
R.M.S On-State Current (Note 3)	$I_T(RMS)$	3000	A
Peak One Cycle Surge On-State Current (Non Repetitive, 10ms-Width Half Sine Waveform)	I_{TSM}	46000	A
Critical Rate of Rise of On-State Current (Note 4)	di/dt	300	A / μs
Peak Forward Gate Current	I_{FGM}	200	A
Average Forward Gate Power Dissipation	$P_{FG}(AV)$	190	W
Average Reverse Gate Reverse Dissipation	$P_{RG}(AV)$	550	W
R.M.S Gate Current (Note 5)	$I_G(RMS)$	84	A
Peak Reverse Gate Voltage (At Static)	V_{RGM}	17	V
Operation Junction Temperature Range	T_j	-40~115	°C
Storage Temperature Range	T_{stg}	-40~115	°C
Mounting Force	—	98~120	kN

(Note 1) $V_{GK} = -10V$ (Note 2) $V_D = 2250V$, $V_{DM} \leq 3600V$, $C_S \geq 6\mu F$, $di_{GQ}/dt \geq 60A/\mu s$, $V_{DSP} \leq 1200V$, $L_S \leq 80nH$ (non-snubber)(Note 3) 50Hz Half Sine Waveform, $T_j = 80^\circ C$ (Note 4) $V_D \leq 2250V$, $I_{TM} \leq 4500A$, $I_G \geq 100A$ ($t_r \leq 1\mu s$), $f \leq 50Hz$, $C_S \leq 6\mu F$, $R_S \geq 5\Omega$, $25^\circ C \leq T_j \leq 115^\circ C$ (Note 5) Ambient Temperature of coaxial gate-cathode lead = $90^\circ C$ 

JEDAC —

EIAJ —

TOSHIBA —

Weight : 6000g

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ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Repetitive Peak Off-State Current	I_{DRM}	$V_{\text{DRM}} = 4500\text{V}$, $V_{\text{GK}} = -10\text{V}$ $T_j = 115^\circ\text{C}$	—	—	300	mA
Repetitive Peak Reverse Current	I_{RRM}	$V_{\text{RRM}} = 4000\text{V}$ $T_j = 115^\circ\text{C}$	—	—	300	mA
Repetitive Peak Reverse Gate Current	I_{RGM}	$V_{\text{RGM}} = 17\text{V}$ $T_j = 125^\circ\text{C}$	—	—	10	mA
Peak On-State Voltage	V_{TM}	$I_{\text{TM}} = 4500\text{A}$, $T_j = 115^\circ\text{C}$	—	—	4.0	V
Gate Trigger Voltage	V_{GT}	$V_{\text{D}} = 24\text{V}$ $R_{\text{L}} = 0.1\Omega$	$T_j = -40^\circ\text{C}$	—	—	V
			$T_j = 25^\circ\text{C}$	—	2.0	V
Gate Trigger Current	I_{GT}		$T_j = -40^\circ\text{C}$	—	—	A
			$T_j = 25^\circ\text{C}$	—	10	A
Turn-On Delay Time	t_{d}	$V_{\text{D}} = 2250\text{V}$, $I_{\text{TM}} = 4500\text{A}$ $di_{\text{F}}/dt = 300\text{A}/\mu\text{s}$	—	—	4.0	μs
Turn-On Time	t_{gt}	$I_{\text{GM}} = 100\text{A}$ ($t_{\text{r}} = 1\mu\text{s}$) $T_j = 25^\circ\text{C}$, non-snubber	—	—	12	μs
Critical Rate of Rise of Off-State Voltage	dv/dt	$V_{\text{DRM}} = 2250\text{V}$ $T_j = 115^\circ\text{C}$, $V_{\text{GK}} = -10\text{V}$ Exponential Rise	1000	—	—	$\text{V}/\mu\text{s}$
Storage Time	t_{s}	$I_{\text{TGQ}} = 4500\text{A}$	—	—	45	μs
Gate Turn-Off Time	t_{gq}	$V_{\text{DM}} = 3600\text{V}$, $T_j = 115^\circ\text{C}$	—	—	48	μs
Tail Time	t_{tail}	$V_{\text{D}} = 2000\text{V}$, $C_{\text{S}} = 6\mu\text{F}$ $di_{\text{GQ}}/dt = 60\text{A}/\mu\text{s}$	—	—	800	μs
Gate Turn-Off Current	I_{GQ}	Off squeeze current $\geq 600\text{mA}$	—	—	1500	A
Thermal Resistance	$R_{\text{th(j-f)}}$	Junction to fin	—	—	0.0043	$^\circ\text{C}/\text{W}$
Reverse Recovery Charge	Q_{rr}	$I_{\text{T}} = 2000\text{A}$, $V_{\text{R}} = 1500\text{V}$ $di_{\text{T}}/dt = -300\text{A}/\mu\text{s}$, $C_{\text{S}} = 6\mu\text{F}$ $R_{\text{S}} = 5\Omega$, $T_j = 115^\circ\text{C}$	$V_{\text{TM}} \leq 2.6\text{V}$		15000	μC
			$V_{\text{TM}} = 4.0\text{V}$		8000	

